



Material Content Data Sheet



Sales Product Name		SPB80N06S-08		Issued		29. August 2013			
MA#		MA000532034							
Package		PG-TO263-3-2		Weight*		1468.61 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	13.370	0.91	0.91	9104	9104	
leadframe	non noble metal	iron	7439-89-6	0.853	0.06		581		
	inorganic material	phosphorus	7723-14-0	0.256	0.02		174		
	non noble metal	copper	7440-50-8	851.691	57.98	58.06	579930	580685	
wire	non noble metal	aluminium	7429-90-5	4.801	0.33	0.33	3269	3269	
encapsulation	organic material	carbon black	1333-86-4	8.695	0.59		5920		
	plastics	epoxy resin	-	95.644	6.51		65125		
	inorganic material	silicondioxide	60676-86-0	475.321	32.37	39.47	323653	394698	
leadfinish	non noble metal	tin	7440-31-5	9.657	0.66	0.66	6575	6575	
plating	non noble metal	nickel	7440-02-0	0.228	0.02		156		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	0	156	
solder	noble metal	silver	7440-22-4	0.202	0.01		138		
	non noble metal	tin	7440-31-5	0.162	0.01		110		
	non noble metal	lead	7439-92-1	7.733	0.53	0.55	5265	5513	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com